

Title (en)
Lead-free, free-cutting copper alloys

Title (de)
Bleifreie Automatenkupferlegierung

Title (fr)
Alliage de cuivre de décolletage sans plomb

Publication
EP 1600517 A3 20051214 (EN)

Application
EP 05017191 A 19981116

Priority

- EP 98953071 A 19981116
- JP 28859098 A 19981012

Abstract (en)
[origin: EP1559802A1] Lead-free copper alloys with industrially satisfactory machinability comprising 69 to 79 percent, by weight, of copper, 2.0 to 4.0 percent, by weight, of silicon, and the remaining percent, by weight, of zinc. <IMAGE>

IPC 1-7
C22C 9/04; C22F 1/08

IPC 8 full level
C22F 1/00 (2006.01); **C22C 9/04** (2006.01); **C22F 1/08** (2006.01)

CPC (source: EP KR)
C22C 9/04 (2013.01 - EP KR); **C22F 1/08** (2013.01 - EP)

Citation (search report)

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EP 05075421 A 19981116; AU 1054199 A 19981116; CA 2314144 A 19981116; DE 69832097 T 19981116; DE 69838115 T 19981116; DE 69839830 T 19981116; DE 69840585 T 19981116; EP 05017189 A 19981116; EP 05017190 A 19981116; EP 05017191 A 19981116; EP 98953071 A 19981116; JP 28859098 A 19981012; JP 9805157 W 19981116; KR 20007006434 A 20000612; TW 88103879 A 19990312